

### Dual Power Schottky Diode

in ISOPLUS i4-PAC™

**Rectifier Bridge** 

Conditions

 $T_c = 25^{\circ}C$ 

Conditions

 $T_{c} = 90^{\circ}C$ ; sine 180°

 $T_c = 90^{\circ}C; d = 0.5$  rectangular

Symbol

 $V_{\text{RRM}}$ 

 $\mathbf{I}_{FAV}$ 

**P**<sub>tot</sub>

I<sub>F(AV)M</sub>

Symbol







**Maximum Ratings** 

V

А

А

W

80

85

90

100

**Characteristic Values** 

 $(T_{v_1} = 25^{\circ}C)$ , unless otherwise specified)



#### Features

- Schottky diodes
- very low forward voltage
- extremely fast switching
- blocking capability optimized for elevated temperature
- ISOPLUS i4-PAC<sup>™</sup> package
  - DCB isolated back surface
  - enlarged creepage towards heatsink
  - application friendly pinout
  - low inductive current path
  - high reliability
  - industry standard outline

#### Applications

- for use in
- automotive drives and converters
- hand held tools
- low voltage power supplies
- battery chargers
- solar converters
- operating
  - as free wheeling diode of choppers for supply of motors or transformers
- as high frequency secondary rectifier
- anti paralleled to MOSFETs complementing their intrinsic body diode

min. typ. max. V V,  $I_{F} = 75 \text{ A}; T_{VJ} = 25^{\circ}\text{C}$ 0.9 1.0  $T_{VJ} = 125^{\circ}C$ 0.8 V  $V_{R} = V_{RRM}; T_{VJ} = 25^{\circ}C$ 2 mΑ I<sub>R</sub>  $T_{VJ} = 125^{\circ}C$ 2.5 mΑ  $R_{thJC}$ (per diode) 1.4 K/W

(per diode)

Data according to IEC 60747 and refer to a single diode unless otherwise stated. IXYS reserves the right to change limits, test conditions and dimensions.

# LIXYS

## FSS 100-008A

Component					
Symbol	Conditions	Maximum R	Maximum Ratings		
T <sub>vj</sub> T <sub>stg</sub>		-55+175 -55+125	°C ℃		
V <sub>ISOL</sub>	I <sub>ISOL</sub> ≤ 1 mA; 50/60 Hz	2500	V~		
F <sub>c</sub>	mounting force with clip	20120	Ν		

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
C <sub>P</sub>	coupling capacity between shorted pins and mounting tab in the case		40	pF
d <sub>s</sub> , d <sub>A</sub> d <sub>s</sub> , d <sub>A</sub>	pin - pin pin - backside metal	5.5 5.5		mm mm
R <sub>thCH</sub>	with heatsink compound		0.15	K/W
Weight			9	g



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Datasheets for electronics components.